

05-16-2003



102449738

Docket No.: 59012 (71987)

R SHEET

U.S. DEPARTMENT OF COMMERCE  
Patent and Trademark Office

LY

Tab settings → → → ▼

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

Ying-Ren LIN  
Ho-Yi TSAI

5-603

Additional names(s) of conveying party(ies)

☐ Yes ☒ No

3. Nature of conveyance:

☒ Assignment

☐ Merger

☐ Security Agreement

☐ Change of Name

☐ Other

Execution Date: February 24, 2003

2. Name and address of receiving party(ies):

Name: Siliconware Precision Industries Co., Ltd.

Address: No. 123, Sec. 3, Da Fong Road, Tantz, Taichung, Taiwan, R.O.C.

City: State/Prov.:

Country: ZIP:

Additional name(s) & address(es)

☐ Yes ☐ No

4. Application number(s) or patent numbers(s):

If this document is being filed together with a new application, the execution date of the application is: May 6, 2003

Patent Application No.

Filing date

05/12/2003 MARZ11 00000034 10434247

03 FC:8021

40.00

Additional numbers

B. Patent No.(s)

☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Peter F. Corless

Registration No. 33,860

Address: EDWARDS & ANGELL, LLP

P.O. Box 9169

City: Boston State/Prov.: MA

Country: USA ZIP: 02209

6. Total number of applications and patents involved:

1

7. Total fee (37 CFR 3.41):.....\$ 40.00

☒ Enclosed - Any excess or insufficiency should be credited or debited to deposit account

☐ Authorized to be charged to deposit account

8. Deposit account number:

04-1105

(Attach duplicate copy of this page if paying by deposit account)

DO NOT USE THIS SPACE

9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Peter F. Corless

Name of Person Signing

Signature

May 6, 2003

Date

2

Total number of pages including cover sheet, attachments, and

Mail documents to be recorded with required cover sheet information to:  
Commissioner of Patents & Trademarks, Box Assignments

PATENT  
REEL: 014061 FRAME: 0079

# ASSIGNMENT OF U.S. PATENT APPLICATION

In consideration of the sum of One Dollar in hand paid, and other good and valuable consideration, the receipt of which is hereby acknowledged, the undersigned

Inventor(s) (1) Ying-Ren LIN (2) Ho-Yi TSAI  
 Full Name(s) \_\_\_\_\_

Hereby sell, assign and transfer to

Assignee SILICONWARE PRECISION INDUSTRIES CO., LTD.  
 Name and Address No. 123, Sec. 3, Da Fong Road, Tantz, Taichung,  
Taiwan, R.O.C.

(hereinafter called the Assignee) the entire right, title, and interest in and to any and all improvements which are disclosed in the Application for United States Letters Patent entitled

Title of Invention: \_\_\_\_\_  
THERMALLY ENHANCED SEMICONDUCTOR PACKAGE WITH EMI SHIELDING

Which application was

Complete either a) executed by the undersigned on \_\_\_\_\_  
 b) filed on the \_\_\_\_\_  
 Serial No. \_\_\_\_\_

Including any and all United States Letters Patents which may be granted therefore and any and all extensions, divisions, reissues, substitutes, renewals or continuations thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property.

It is hereby authorized and requested that the Commissioner of Patents issue any and all of said Letters Patent, when granted, to said assignee.

Further, it is agreed that, when requested, without charge to but at the expense of said Assignee, the undersigned will execute all divisional, continuing, substitute, renewal, and reissue patent applications; execute all rightful other papers; and generally do everything possible which said Assignee shall consider desirable for aiding in securing and maintaining proper patent protection.

Date \_\_\_\_\_ Signed at Taichung, Taiwan, R.O.C.  
 On 24-03

Inventor(s) Y. R. Lin Ying-Ren LIN  
 Full Signature(s) HY Tsai Ho-Yi TSAI